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(12) **United States Design Patent**
Okajima et al.

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- (54) **GAS NOZZLE FOR SUBSTRATE PROCESSING APPARATUS**
- (71) Applicant: **KOKUSAI ELECTRIC CORPORATION**, Tokyo (JP)
- (72) Inventors: **Yusaku Okajima**, Tokyo (JP); **Toru Kagaya**, Tokyo (JP); **Hiroaki Hiramatsu**, Tokyo (JP); **Shinya Ebata**, Tokyo (JP)
- (73) Assignee: **KOKUSAI ELECTRIC CORPORATION**, Tokyo (JP)
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- (51) **LOC (12) Cl.** **23-01**
- (52) **U.S. Cl.**
USPC **D23/213**
- (58) **Field of Classification Search**
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CPC F23D 14/045; F23D 14/16; F23D 14/48; F23D 14/50; F23D 2203/10; F23D 2203/1012; F32D 14/10; B24B 9/007; B08B 9/00; B08B 9/021; B08B 9/032; B08B 9/027; B08B 9/02
See application file for complete search history.

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Primary Examiner — Derrick E Holland
Assistant Examiner — Andrew Kerr
(74) *Attorney, Agent, or Firm* — Fitch, Even, Tabin & Flannery LLP

(57) **CLAIM**

We claim the ornamental design for a gas nozzle for substrate processing apparatus, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and left side perspective view of a gas nozzle for substrate processing apparatus showing our new design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a rear elevational view thereof;
FIG. 4 is a left side elevational view thereof;
FIG. 5 is a right side elevational view thereof;
FIG. 6 is a top plan view thereof;
FIG. 7 is a bottom plan view thereof.
FIG. 8 is a cross-sectional view take along line 8-8 in FIG. 2 thereof;
FIG. 9 is an enlarged portion view taken along line 9-9 in FIG. 2 thereof; and,
FIG. 10 is an enlarged portion view taken along line 10-10 in FIG. 8.
The broken lines shown in the drawings represent portions of the gas nozzle for substrate processing apparatus that form no part of the claimed design.

1 Claim, 4 Drawing Sheets



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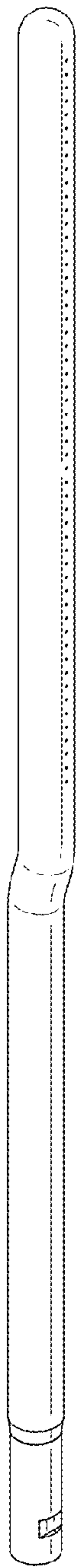


FIG. 1

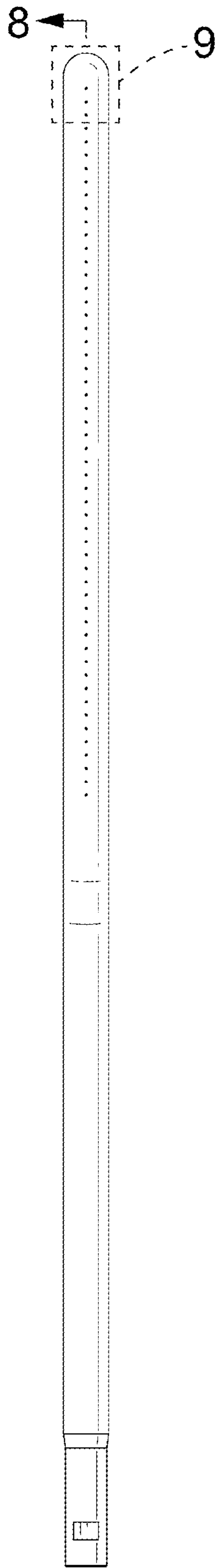


FIG. 2

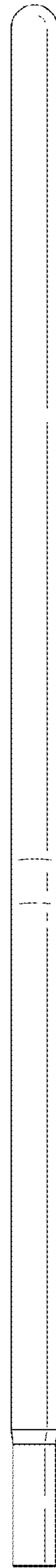


FIG. 3

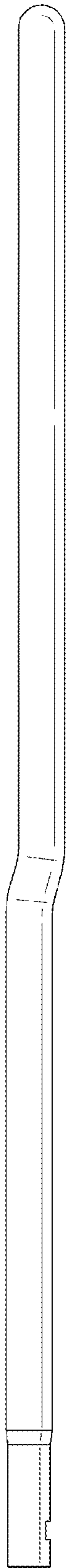


FIG. 4

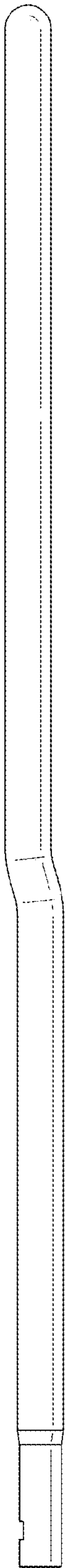


FIG. 5



FIG. 6



FIG. 7

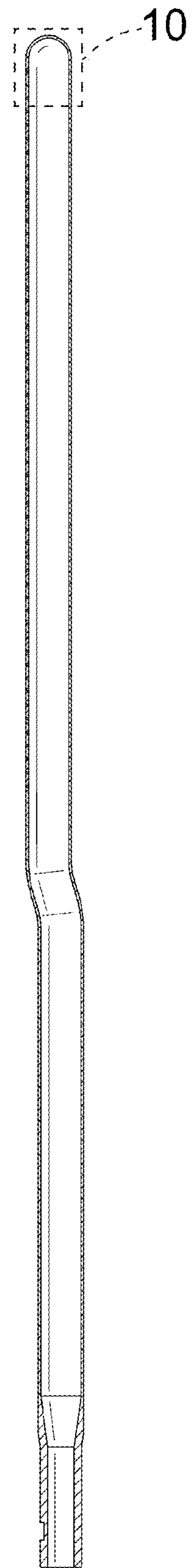


FIG. 8

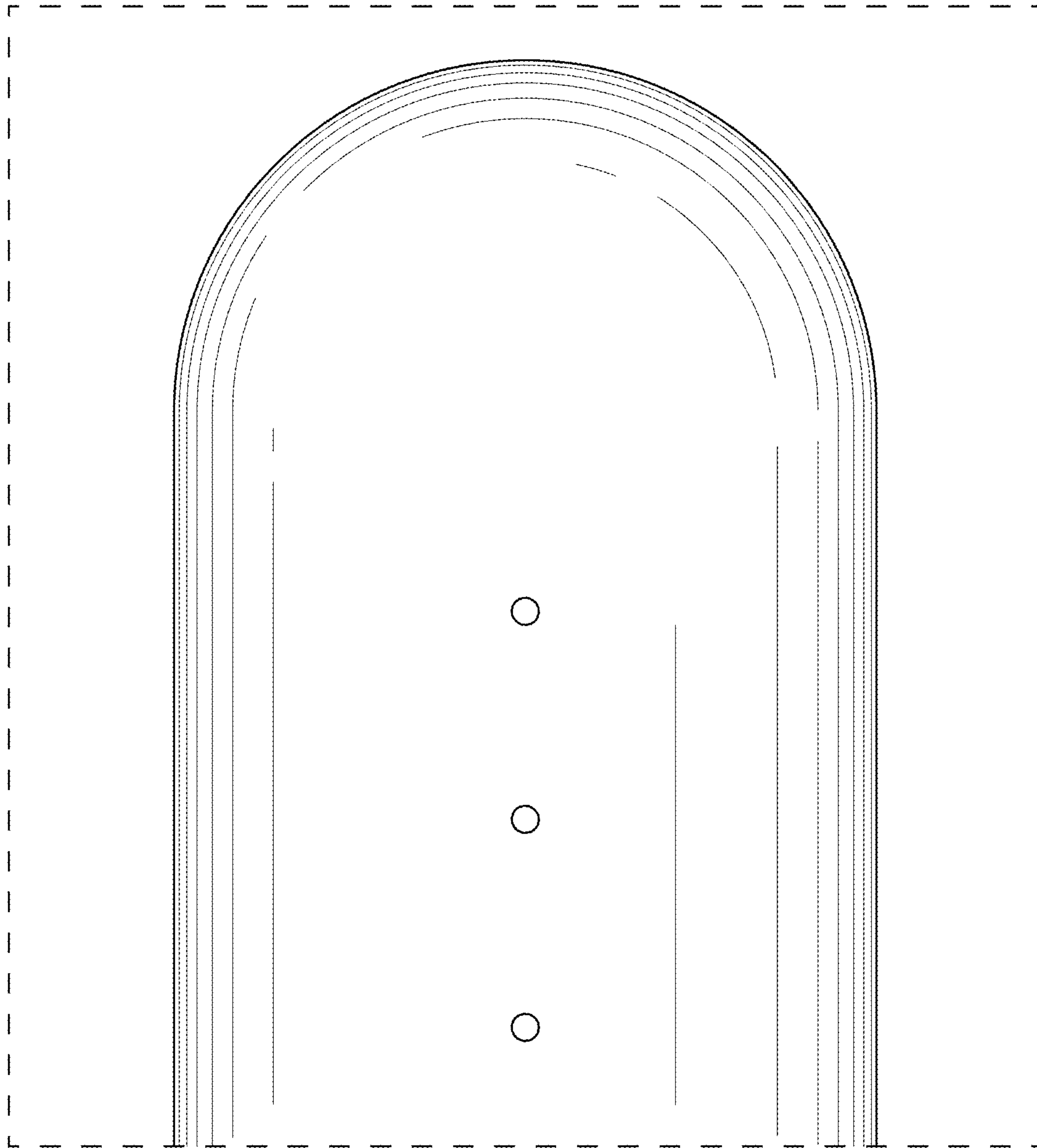


FIG. 9

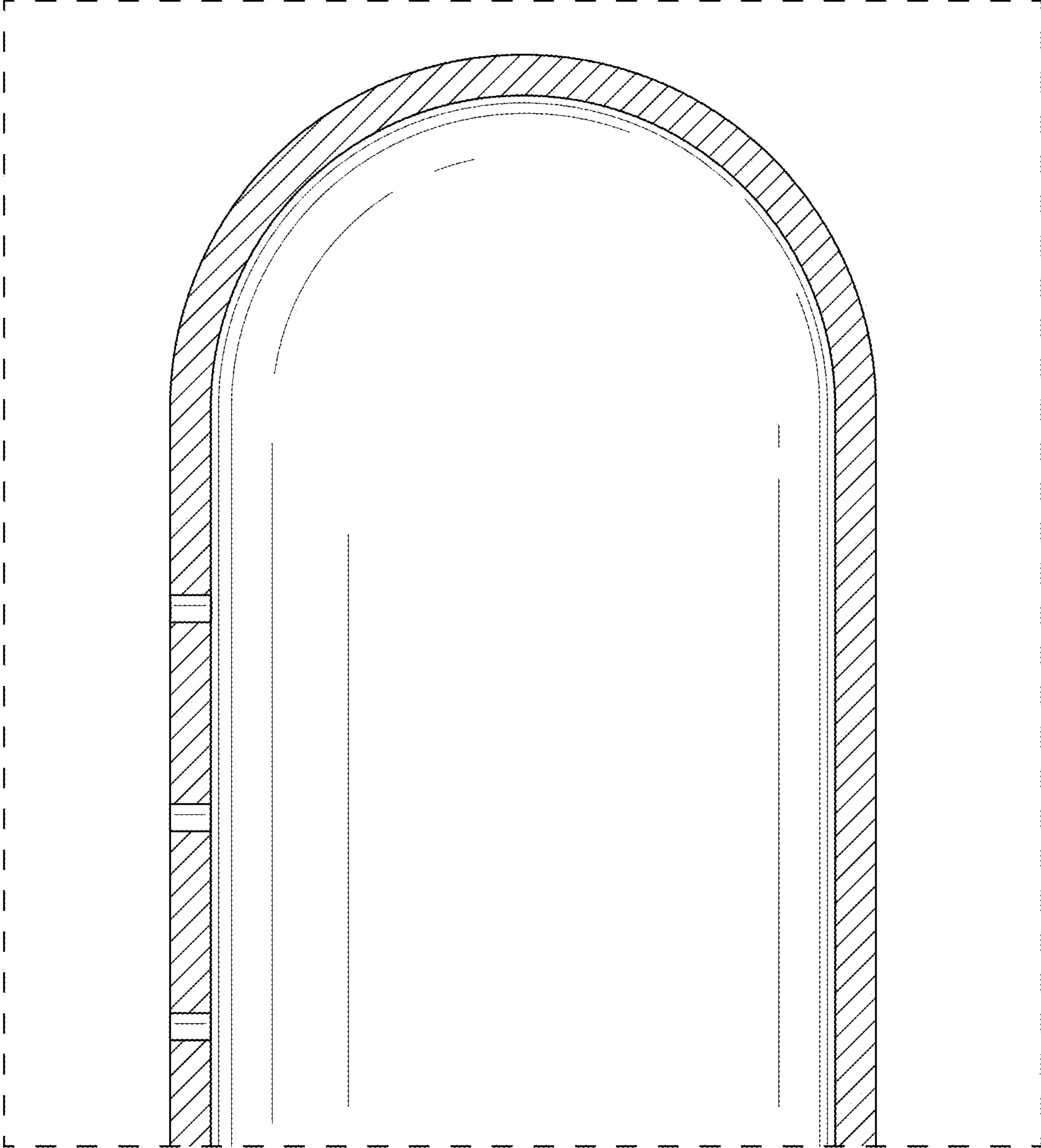


FIG. 10